AA5060SURC/E

HYPER RED

Features

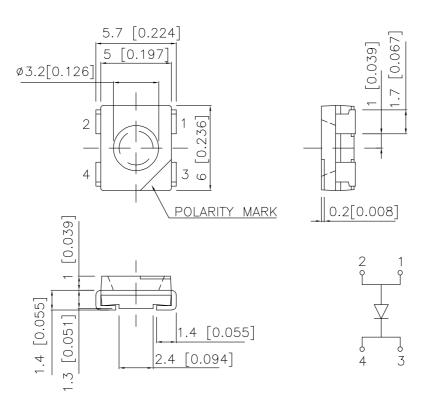
- SINGLE COLOR.
- SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- AVAILABLE ON TAPE AND REEL.
- IDEAL FOR BACKLIGHTING.
- PACKAGE: 500PCS / REEL.
- •RoHS COMPLIANT.

.

Description

The Hyper Red source color devices are made with DH InGaAIP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25 (0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

SPEC NO: DSAD0897 APPROVED: J. Lu REV NO: V.3 CHECKED: Allen Liu DATE: MAR/08/2005 DRAWN: S.H.CHEN PAGE: 1 OF 4 ERP:1201000536

Kingbright

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) @ 50mA		Viewing Angle
			Min.	Тур.	201/2
AA5060SURC/E	HYPER RED (InGaAIP)	WATER CLEAR	380	700	100°

Note:

Electrical / Optical Characteristics at Ta=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	640		nm	I _F =20mA
λD	Dominant Wavelength	Hyper Red	630		nm	I _F =20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	25		nm	I _F =20mA
С	Capacitance	Hyper Red	45		pF	V _F =0V;f=1MHz
V _F	Forward Voltage	Hyper Red	1.9	2.5	V	I _F =20mA
I _R	Reverse Current	Hyper Red		10	uA	V _R = 5V

Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red	Units	
Power dissipation	125	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	200	mA	
Reverse Voltage	5	V	
Operating / Storage Temperature	-40°C To +85°C		

Note

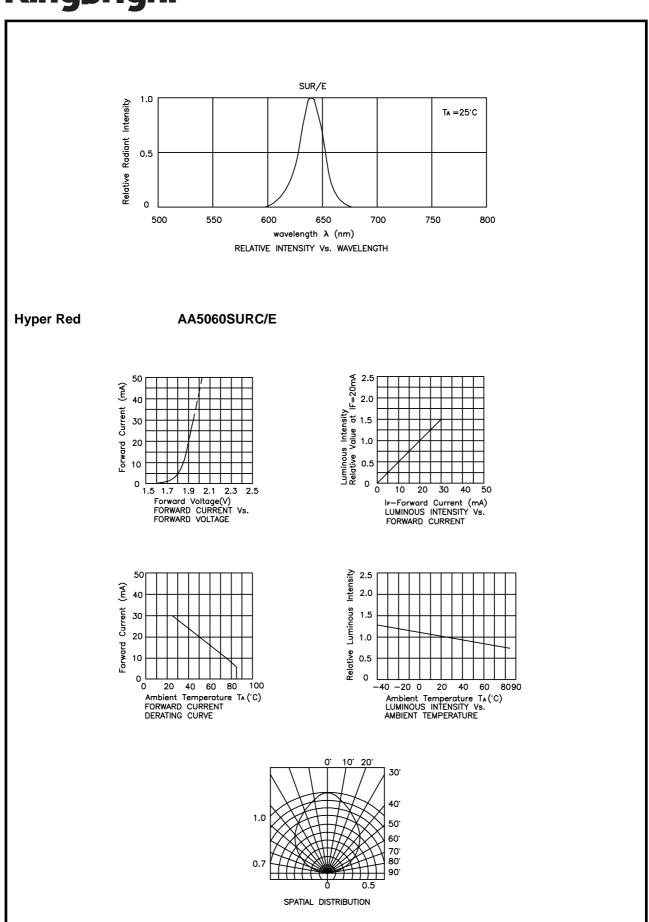
 SPEC NO: DSAD0897
 REV NO: V.3
 DATE: MAR/08/2005
 PAGE: 2 OF 4

 APPROVED: J. Lu
 CHECKED: Allen Liu
 DRAWN: S.H.CHEN
 ERP:1201000536

^{1.} θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

^{1. 1/10} Duty Cycle, 0.1ms Pulse Width.

Kingbright



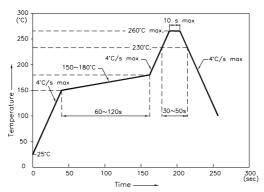
 SPEC NO: DSAD0897
 REV NO: V.3
 DATE: MAR/08/2005
 PAGE: 3 OF 4

 APPROVED: J. Lu
 CHECKED: Allen Liu
 DRAWN: S.H.CHEN
 ERP:1201000536

Kingbright

AA5060SURC/E

Reflow Soldering Profile For Lead-free SMT Process.



- NOTES:

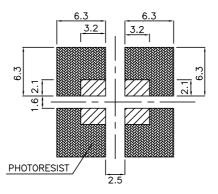
 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

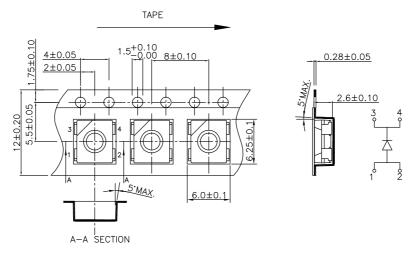
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern

(Units: mm)



Tape Specifications (Units: mm)



Remarks:

If there is sorting requirement (eg. forward voltage, luminous intensity or wavelength), the condition as follows:

- 1. Wavelength: +/-1nm (Test condition is based on the sorting standard).
- 2.Luminous intensity: +/-15% (Test condition is based on the sorting standard).
- 3. Forward voltage: +/-0.1V (Test condition is based on the sorting standard).

DATE: MAR/08/2005 PAGE: 4 OF 4 SPEC NO: DSAD0897 **REV NO: V.3** APPROVED: J. Lu ERP:1201000536 **CHECKED: Allen Liu** DRAWN: S.H.CHEN